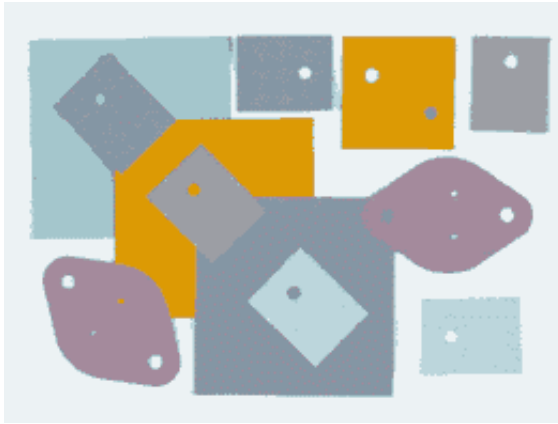


Thermal Pads T-177 / T-228



Trocad Thermally Conductive Insulators Pads are designed to be clean, grease free and flexible. The combination of a tough carrier material such as fibreglass and silicone rubber which is conformable, provides the engineer with a more versatile material than mica or ceramics and grease. T-Pads minimize the thermal resistance from the case of a power semiconductor to the heat sink. T-Pads electrically isolate the semiconductor from the heat sink and have sufficient dielectric strength to withstand high voltage. They are also tough to resist puncture by the facing metal surface.

T-177/T-228 Pads are ideally suitable where low thermal resistance and low cost are critical.

Trocad T-Pads are available in various TO outlines, in sheets or can be made to your outline drawing.

Typical Properties	T 177	T 228	Test Standard
Part prefix code	T177	T228	
Thickness (mm)	0.177+0.03 -0.01	0.228 ±0.02	
Breakdown voltage 50Hz RMS	3500	4500	ASTM D149
Approx Thermal Resistance (to -3 transistor) °C/Watt	0.45	0.50	ASTM D5470
Hardness	80 ±5	80 ±5	Shore Micro
Tear Resistance kN/m	50	50	ASTM D624

Tensile Strength MPa	16	16	ASTM D412
Dielectric Constant 1000Hz	2.6	2.6	ASTM D150
Elongation %	30	30	ASTM D412
Continuous Use Temp. °C	-60 to +180	-60 to +180	
Colour	Grey	Grey	